

I CLAIM:

1 ~~1.~~ A method for processing a substrate having an
2 initial surface roughness R_0 to modify the surface
3 roughness to a final surface roughness R_F , comprising:

4 (a) applying a first wavelength of laser light to
5 the substrate surface to modify the surface roughness on
6 at least a portion of the surface to an intermediate
7 surface roughness R_I ; and

8 (b) applying a second wavelength of laser light to
9 said portion of the substrate surface having an
10 intermediate surface roughness R_I , to modify the surface
11 roughness of on at least a part of said portion to an
12 final surface roughness R_F .

1 2. The method of claim 1 wherein the first wavelength
2 is greater than the second wavelength.

1 3. The method of claim 1 wherein the first wavelength
2 is less than the second wavelength.

- 1 4. A method for processing a substrate, comprising:
- 2 (a) applying a first wavelength of laser light to
- 3 a portion of the substrate; and
- 4 (b) applying a second wavelength of laser light to
- 5 said portion of the substrate.